



Material Content Data Sheet



Sales Product Name				IPD90N06S4-05		Issued		22. January 2018	
MA#				MA000983322					
Package				PG-TO252-3-11		Weight*		376.07 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	3.393	0.90	0.90	9023	9023	
leadframe	non noble metal	iron	7439-89-6	0.215	0.06		572		
	inorganic material	phosphorus	7723-14-0	0.065	0.02		172		
	non noble metal	copper	7440-50-8	215.017	57.17	57.25	571744	572488	
wire	non noble metal	aluminium	7429-90-5	45.572	12.12	12.12	121180	121180	
encapsulation	organic material	carbon black	1333-86-4	0.858	0.23		2282		
	plastics	epoxy resin	-	15.019	3.99		39936		
	inorganic material	silicondioxide	60676-86-0	69.944	18.60	22.82	185986	228204	
leadfinish	non noble metal	tin	7440-31-5	3.740	0.99	0.99	9945	9945	
plating	non noble metal	nickel	7440-02-0	0.091	0.02		241		
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.02	1	242	
solder	noble metal	silver	7440-22-4	0.074	0.02		196		
	non noble metal	tin	7440-31-5	0.059	0.02		157		
	non noble metal	lead	7439-92-1	2.822	0.75	0.79	7505	7858	
heatspreader	non noble metal	iron	7439-89-6	0.019	0.01		51		
	inorganic material	phosphorus	7723-14-0	0.006	0.00		15		
	non noble metal	copper	7440-50-8	19.177	5.10	5.11	50994	51060	
*deviation	< 10%					Sum in total:	100.00	1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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